

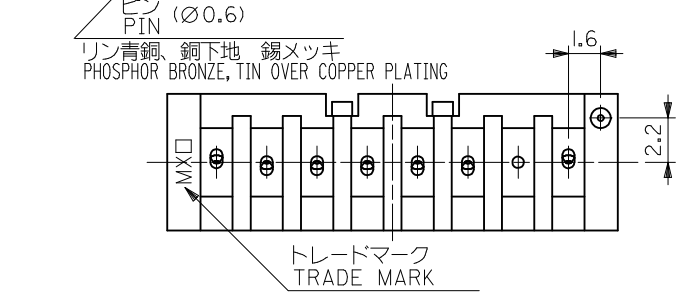
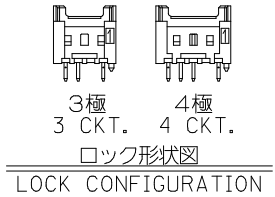
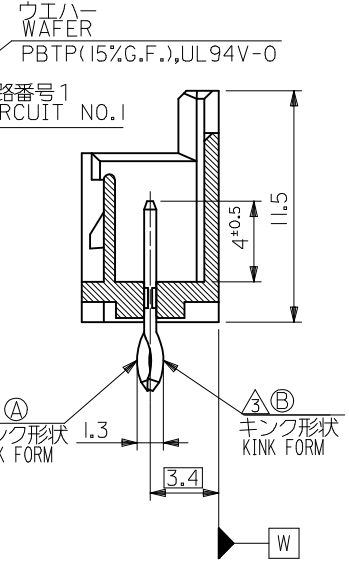
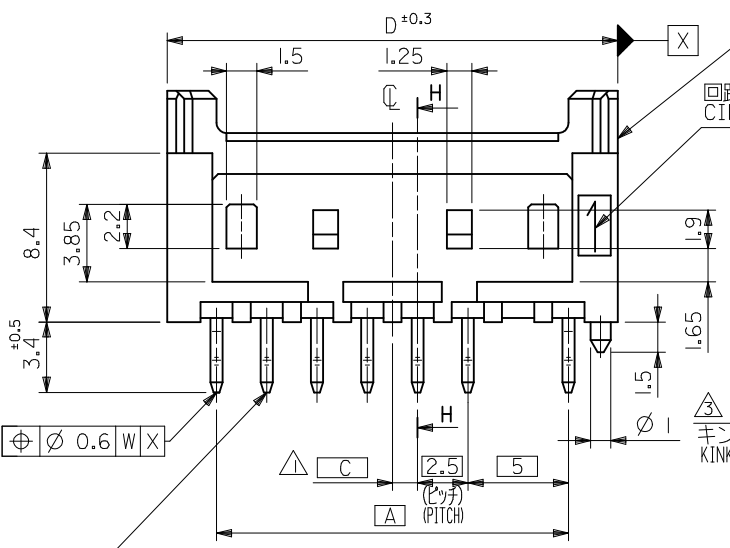
注記  
NOTES

△ ウエハの  $\phi$  から隣接するピンの  $\phi$  までの位置を示す。  
SHOW POSITION FROM  $\phi$  OF WAFER TO  $\phi$  OF ADJACENT PIN.

2. 嵌合相手：51102,51103 シリーズ  
MATES WITH : 51102,51103 SERIES.

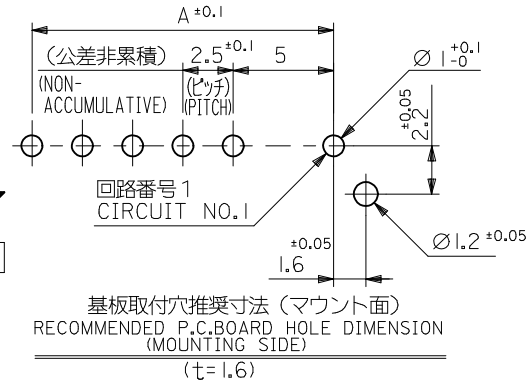
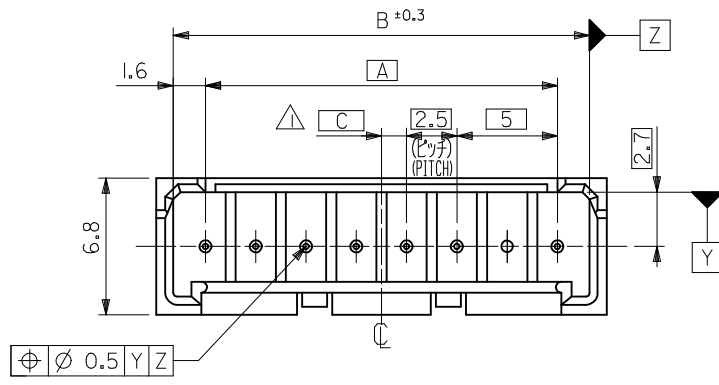
△ キングの形状は両サイドが (A)、その他の極はすべて (B) 形状とする。  
KINK FORM MORE THAN 2 CURCUIT: PINS AT BOTH ENDS ARE KINK FORMED TO (A), THE OTHER PINS ARE KINK FORMED TO (B).

基板取付穴推奨寸法 (マウント面)  
RECOMMENDED P.C.BOARD HOLE DIMENSION (MOUNTING SIDE)  
( $\tau=1.6$ )



24.9	2.5	23.2	20	53389-0810	8
19.9	2.5	18.2	15	53389-0610	6
12.4	3.25	10.7	7.5	53389-0310	3
D	C	B	A	MATERIAL NO.	極数 NO. OF CKTS.

REVISED EC NO: J2017-0224 DRW: M. SHIKAWA 2016/10/12 CHKD: K. TAKAHASHI 2016/10/12 APPR: M. SASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±	DRAWN BY K. TOJO	DATE '92/12/22	TITLE 5/2.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-		
	0.25 OVER 0.5 UNDER	±	CHECKED BY M. FUKUSHIMA	DATE '96/7/24			
	0.5 OVER 1.0 UNDER	±	APPROVED BY M. FUKUSHIMA	DATE '96/7/24			
0 OVER 10 UNDER	±0.2	MATERIAL NO.	DOCUMENT NO.	SEE CHART		SD-53389-001	SHEET NO. 1 OF 1
10 OVER 30 UNDER	±0.25	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
30 OVER	±0.3						



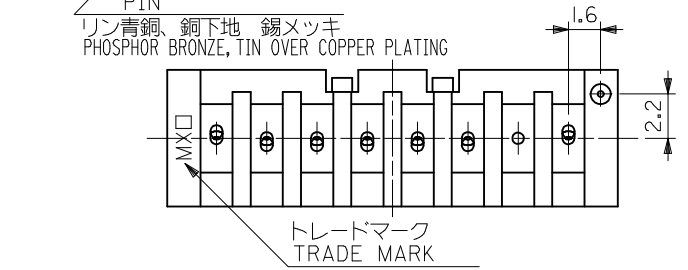
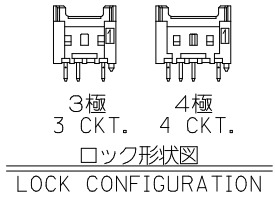
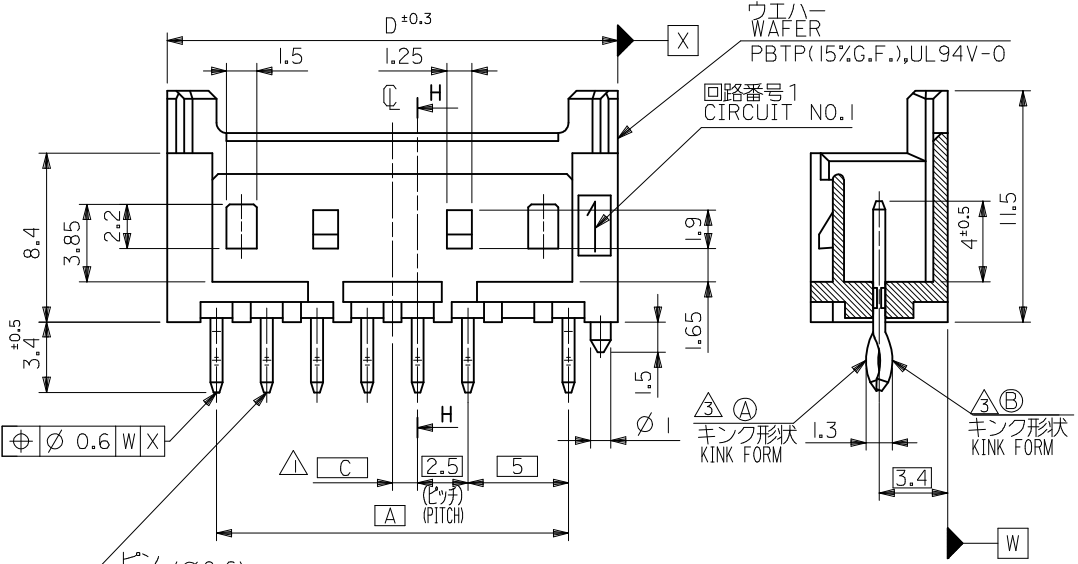
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( $\tau=1.6$ )



断面 H-H  
SECT. H-H

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19.9	2.5	18.2	15	53389-0610	6
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30 OVER	±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					